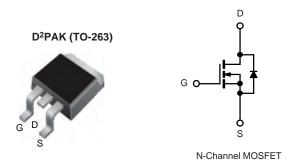


N-Channel 40 V (D-S) MOSFET

| PRODUCT SUMMARY | | | | | |
|---------------------|-----------------------------------|------------------------------------------|--------|--|--|
| V _{DS} (V) | R _{DS(on)} (Ω) | $R_{DS(on)}(\Omega)$ $I_D(A)^{a, c} Q_g$ | | | |
| 40 | 0.0017 at V _{GS} = 10 V | 150 | 120 nC | | |
| | 0.0025 at V _{GS} = 4.5 V | 135 | 120110 | | |



FEATURES

- TrenchFET[®] Power MOSFET
- 100 % R_g and UIS Tested

APPLICATIONS

- Synchronous Rectification
- Power Supplies

| Parameter | | Symbol | Limit | Unit | |
|-------------------------------------------------------------------------------|-----------------------------------|-----------------|---------------------|------|--|
| Drain-Source Voltage | V _{DS} | 40 | V | | |
| Gate-Source Voltage | | V _{GS} | | ± 25 | |
| | T _C = 25 °C | | 150 ^{a, c} | A | |
| Continuous Drain Current (T 175 °C) | T _C = 70 °C | | 120 ^c | | |
| Continuous Drain Current (T _J = 175 °C) | T _A = 25 °C | I _D | 29 ^b | | |
| | T _A = 70 °C | | 23 ^b | | |
| Pulsed Drain Current | | I _{DM} | 380 | | |
| Avalanche Current Pulse L = 0.1 mH Single Pulse Avalanche Energy L = 0.1 mH | | I _{AS} | 80 | | |
| | | E _{AS} | 320 | mJ | |
| Continuous Source-Drain Diode Current | T _C = 25 °C | I _S | 110 ^{a, c} | — A | |
| Continuous Source-Drain Diode Current | T _A = 25 °C | 'S | 2.6 ^b | | |
| | T _C = 25 °C | | 312 ^a | w | |
| Maximum Power Dissipation | T _C = 70 °C | P | 200 | | |
| | T _A = 25 °C | P _D | 3.13 ^b | | |
| | T _A = 70 °C | | 2.0 ^b | | |
| Operating Junction and Storage Temperature R | T _J , T _{stg} | - 55 to 150 | °C | | |

| THERMAL RESISTANCE RATINGS | | | | | | |
|------------------------------------------|--------------|------------------------------------|---------|---------|------|--|
| Parameter | | Symbol | Typical | Maximum | Unit | |
| Maximum Junction-to-Ambient ^b | Steady State | R _{thJA} | 32 | 40 | °C/W | |
| Maximum Junction-to-Case | Steady State | v State R _{thJC} 0.33 0.4 | | 0,11 | | |

Notes:

a. Based on T_C = 25 °C.

b. Surface Mounted on 1" x 1" FR4 board.

c. Calculated based on maximum junction temperature. Package limitation current is 110 A.

| SPECIFICATIONS $T_J = 25$ °C, unless otherwise noted | | | | | | | | |
|-------------------------------------------------------------|-------------------------|-----------------------------------------------------------------------------------------------------|------|--------|-------|-------|--|--|
| Parameter | Symbol | Test Conditions | Min. | Тур. | Max. | Unit | | |
| Static | N | <u>)/ 0)// 050 vA</u> | 45 | | [| | | |
| Drain-Source Breakdown Voltage | V _{DS} | $V_{GS} = 0 V, I_D = 250 \mu A$ | 45 | | | V | | |
| V _{DS} Temperature Coefficient | | $\Delta V_{DS}/T_J$ I _D = 250 µA | | 41 | | mV/°C | | |
| V _{GS(th)} Temperature Coefficient | $\Delta V_{GS(th)}/T_J$ | | | - 8 | | | | |
| Gate-Source Threshold Voltage | V _{GS(th)} | $V_{DS} = V_{GS}, I_D = 250 \ \mu A$ | 1.2 | | 2.5 | V | | |
| Gate-Source Leakage | I _{GSS} | $V_{DS} = 0 V, V_{GS} = \pm 20 V$ | | | ± 100 | nA | | |
| Zero Gate Voltage Drain Current | I _{DSS} | $V_{DS} = 40 \text{ V}, \text{ V}_{GS} = 0 \text{ V}$ | | | 1 µ | | | |
| | | $V_{DS} = 40$ V, $V_{GS} = 0$ V, $T_{J} = 55$ °C | | | 10 | μ., | | |
| On-State Drain Current ^a | I _{D(on)} | $V_{DS} \ge 5$ V, V_{GS} = 10 V | 120 | | | A | | |
| Drain Source On State Resistance ^a | R _{DS(on)} | $V_{GS} = 10 \text{ V}, \text{ I}_{D} = 30 \text{ A}$ | | 0.0017 | | - Ω | | |
| Drain-Source On-State Resistance ^a | | $V_{GS} = 4.5 \text{ V}, \text{ I}_{D} = 20 \text{ A}$ | | 0.0025 | | | | |
| Forward Transconductance ^a | 9 _{fs} | $V_{DS} = 15 \text{ V}, \text{ I}_{D} = 30 \text{ A}$ | | 180 | | S | | |
| Dynamic ^b | | | | | | | | |
| Input Capacitance | C _{iss} | | | 9000 | | pF | | |
| Output Capacitance | C _{oss} | V_{DS} = 20 V, V_{GS} = 0 V, f = 1 MHz | | 650 | | | | |
| Reverse Transfer Capacitance | C _{rss} | | | 450 | | | | |
| Total Gate Charge | Qg | | | 120 | 180 | nC | | |
| Gate-Source Charge | Q _{gs} | $V_{DS} = 20 \text{ V}, \text{ V}_{GS} = 10 \text{ V}, \text{ I}_{D} = 20 \text{ A}$ | | 30 | | | | |
| Gate-Drain Charge | Q _{gd} | | | 16 | | | | |
| Gate Resistance | Rg | f = 1 MHz | | 0.85 | 1.3 | Ω | | |
| Turn-On Delay Time | t _{d(on)} | | | 20 | 30 | | | |
| Rise Time | t _r | V_{DD} = 20 V, R_{L} = 1.0 Ω | | 11 | 17 | - ns | | |
| Turn-Off Delay Time | t _{d(off)} | $\text{I}_\text{D}\cong\text{20}$ A, V_GEN = 10 V, R_g = 1 Ω | | 77 | 115 | | | |
| Fall Time | t _f | | | 10 | 15 | | | |
| Turn-On Delay Time | t _{d(on)} | | | 102 | 155 | | | |
| Rise Time | t _r | $V_{DD} = 20 \text{ V}, \text{ R}_{L} = 1.0 \Omega$ | | 62 | 95 | | | |
| Turn-Off Delay Time | t _{d(off)} | $I_D \cong 20$ Å, $V_{GEN} = 4.5$ V, $R_g = 1 \Omega$ | | 180 | 270 | | | |
| Fall Time | t _f | | | 60 | 90 | | | |
| Drain-Source Body Diode Characteristic | s | | | | | • | | |
| Continuous Source-Drain Diode Current | ا _S | T _C = 25 °C | | | 110 | ^ | | |
| Pulse Diode Forward Current ^a | I _{SM} | | | | 200 | A | | |
| Body Diode Voltage | V _{SD} | I _S = 20 A | | 0.8 | 1.2 | V | | |
| Body Diode Reverse Recovery Time | t _{rr} | | | 50 | 75 | ns | | |
| Body Diode Reverse Recovery Charge | | | | 70 | 105 | nC | | |
| Reverse Recovery Fall Time | t _a | - I _F = 20 A, di/dt = 100 A/µs, T _J = 25 °C | | 30 | | 1 | | |
| Reverse Recovery Rise Time | t _b | 1 | | 20 | | ns | | |

Notes:

a. Pulse test; pulse width \leq 300 $\mu s,$ duty cycle \leq 2 %.

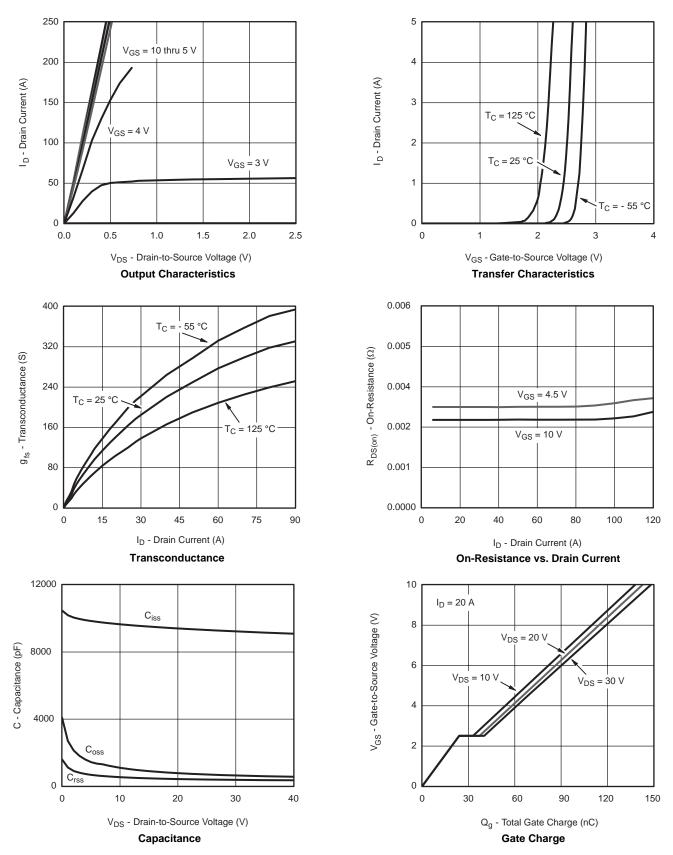
b. Guaranteed by design, not subject to production testing.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

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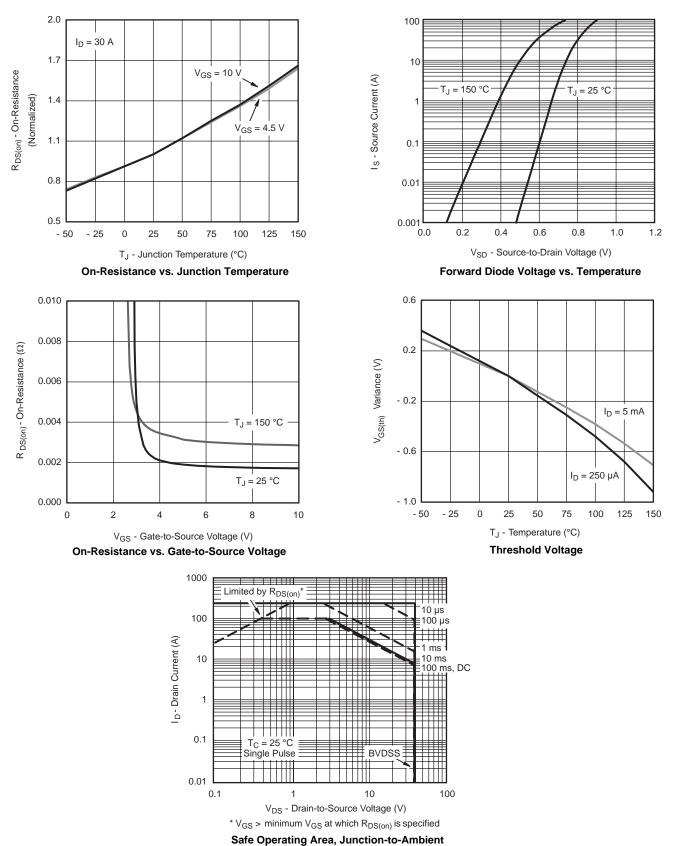
TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



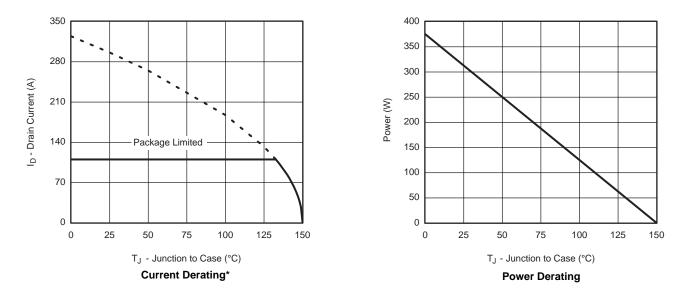
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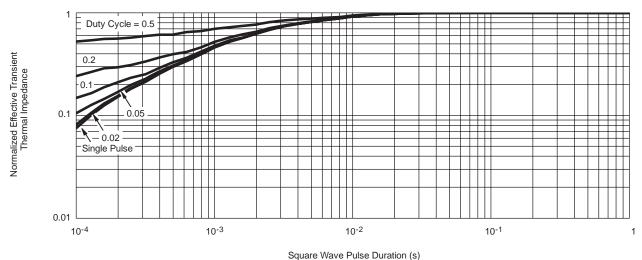






TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted

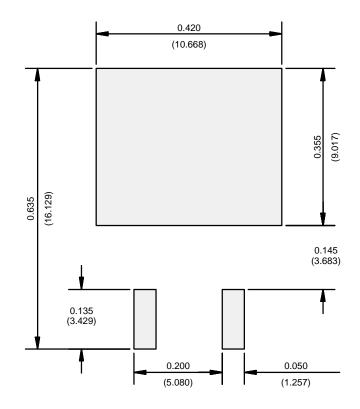
* The power dissipation P_D is based on $T_{J(max)} = 150$ °C, using junction-to-case thermal resistance, and is more useful in settling the upper dissipation limit for cases where additional heatsinking is used. It is used to determine the current rating, when this rating falls below the package limit.



Normalized Thermal Transient Impedance, Junction-to-Case



RECOMMENDED MINIMUM PADS FOR D²PAK: 3-Lead



Recommended Minimum Pads Dimensions in Inches/(mm)



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